

RECORDATION FORM COVER SHEET PATENTS ONLY

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE

TO THE HONORABLE DIRECTOR OF THE UNITED STATES PATENT AND TRADEMARK OFFICE. PLEASE RECORD THE ATTACHED ORIGINAL DOCUMENTS OR COPY THEREOF.

1. Name of conveying parties:

YOU, Chun-Gi

Additional name(s) of conveying party(ies) attached?

☐

Yes

☒

No

2. Name and address of receiving party:

Name: SAMSUNG ELECTRONICS CO., LTD.

Address: 416, Maetan-dong, Yeongtong-gu, Suwon-si,
Gyeonggi-do, Korea

Additional name(s) of receiving party(ies) attached?

☐

Yes

☒

No

3. Nature of Conveyance:

☒

Assignment

☐

Merger

☐

Security Agreement

☐

Change of Name

☐

Other

Execution Date: March 30, 2001

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: _____

A. Patent Application No.(s) 09/755,193

Title: CONTACT STRUCTURE OF WIRING AND A
METHOD FOR MANUFACTURING THE SAME

B. Patent No.(s) 6,885,064

Additional numbers attached?

☐

Yes

☒

No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: David W. Heid

Internal Address: MACPHERSON, KWOK CHEN & HEID LLP

Street Address: 2033 Gateway Place, Suite 400

City San Jose State CA Zip 95110

6. Total number of applications and patents involved: One (1)

7. Total fee (37 CFR 3.41): \$40.00

☒

Authorized to be charged to Deposit Account No. 50-2257.

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Charge Deposit Account No. 50-2257 for any additional fees required for this conveyance and credit Deposit Account No. 50-2257 any amounts overpaid

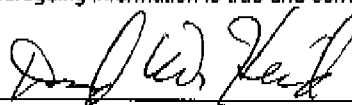
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8. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

David W. Heid, Reg. No. 25,875

Name of Person Signing



Signature

Sept 6, 2001

Date

Total number of pages comprising cover sheet: 1

CH \$40.00 502257 09755193

ASSIGNMENT

In consideration of the sum of One Dollar (\$1.00) or equivalent and other good and valuable consideration paid to each of the undersigned: YOU, Chun-Gi the undersigned hereby sell and assign to Samsung Electronics Co., Ltd. (the Assignee), his/her entire right, title and interest

check applicable box(es) ☒ for the United States of America (as defined in 35 U.S.C. § 100),
☒ and throughout the world,

in the invention(s) known as Contact Structure Of Wiring And A Method For Manufacturing The Same for which application(s) for patent in the United States of America has (have) been executed by the undersigned on March 30, 2001 (also known as United States Application No. 09/755,193, filed January 8, 2001), in any and all applications thereon, in any and all Letters Patent(s) therefor, and in any and all reissues, extensions, renewals, reexaminations of such applications or Letters Patent(s) and divisional and continuation applications thereof, to the full end of the term or terms for which such Letters Patent(s) issue, including all claims, if any, that may have arisen for infringement prior to the date of this assignment, such entire right, title and interest to be held and enjoyed by the above-named Assignee to the same extent as they would have been held and enjoyed by the undersigned had this assignment and sale not been made.

The undersigned agree(s) to execute all papers necessary in connection with the application(s) and any continuing (continuation, divisional, or continuation-in-part), reissue, reexamination or corresponding application(s) thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient.

The undersigned agree(s) to execute all papers necessary in connection with any interference that may be declared concerning the application(s) or any continuing (continuation, divisional, or continuation-in-part), reissue or reexamination application thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

The undersigned hereby represents that the undersigned has full right to convey the entire interest herein assigned, and that the undersigned has not executed, and will not execute, any agreement in conflict therewith.

The undersigned hereby grant(s)

Jason C. Abair, Reg. No. 44,007
 Michael J. Bell, Reg. No. 39,604
 John A. Bendrick, Reg. No. 41,612
 Andrew S. Branc, Reg. No. 45,534
 Celine T. Callahan, Reg. No. 34,301
 Jenny W. Chen, Reg. 44,604
 Mary S. Consalvi, Reg. No. 32,212
 Thomas E. Coverstone, Reg. No. 36,492
 Ben M. Davidson, Reg. No. 38,424
 Ross E. Davidson, Reg. No. 41,698
 James F. Davis, Reg. No. 21,072
 Thomas M. Dunham, Reg. No. 39,965
 Alan M. Grimaldi, Reg. No. 26,599
 J. Jay Guiliano, Reg. No. 41,810
 Albert P. Halluin, Reg. No. 25,227
 Derek J. Jardieu, Reg. No. 44,483
 Christopher L. Kelley, Reg. No. 42,714

Brian S.Y. Kim, Reg. No. 41,114
 Viola T. Kung, Reg. No. 41,131
 Robert C. Laurenson, Reg. No. 34,206
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 Don F. Livornese, Reg. No. 32,040
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 Karen K. Wong, Reg. No. 44,409
 Wallace Wu, Reg. No. 45,380
 Matthew S. Zises, Reg. No. 47,246

of HOWREY SIMON ARNOLD & WHITE, LLP, Box No. 34, 1299 Pennsylvania Ave., NW, Washington, DC 20004-2402, power to insert in this Assignment any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

IN WITNESS WHEREOF, executed by the undersigned on the date(s) opposite their name(s).

Date: March 30, 2001 Signature of Inventor: YOU Chun-Gi
YOU, Chun-Gi

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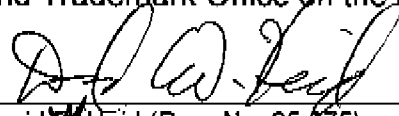
FACSIMILE COVER

Date:	September 6, 2007		
To:	U.S. Patent and Trademark Office	Fax Number #:	(571) 273-0140
	Assignment Division	Telephone Number#	(571) 272-3350
From:	David W. Heid Reg. No. 25,875	Date Sent:	
Subject:	Application No.: 09/755,193 Filing Date: 01/08/2001 Patent No.: 6,885,064 Issue Date: 04/25/2005 Assignee: Samsung Electronics Co., Ltd.	Time Sent:	
Docket No:	AB-1657 US	Fax Operator:	

This transmittal consists of 5 total pages, including this cover sheet.

Message:

I hereby certify that the following documents are being facsimile transmitted to the U.S. Patent and Trademark Office on the date shown below.



David W. Heid (Reg. No. 25,875)

Sept 6, 2007
Date

Enclosed are:

1. Recordation Form Cover Sheet (1 page)(in duplicate); and
2. Assignment (2 pages).

If you do not receive all pages, please call (408) 392-9250

THE INFORMATION CONTAINED IN THIS FACSIMILE MESSAGE IS INTENDED ONLY FOR THE PERSONAL AND CONFIDENTIAL USE OF THE DESIGNATED RECIPIENT(S) NAMED ABOVE. THIS MESSAGE MAY BE AN ATTORNEY-CLIENT COMMUNICATION, AND AS SUCH IS PRIVILEGED AND CONFIDENTIAL. IF THE READER OF THIS MESSAGE IS NOT THE INTENDED RECIPIENT OR AN AGENT RESPONSIBLE FOR DELIVERING IT TO THE INTENDED RECIPIENT, YOU ARE HEREBY NOTIFIED THAT YOU HAVE RECEIVED THIS DOCUMENT IN ERROR AND THAT ANY REVIEW, DISSEMINATION, DISTRIBUTION OR COPYING OF THIS MESSAGE IS STRICTLY PROHIBITED. IF YOU HAVE RECEIVED THIS COMMUNICATION IN ERROR, PLEASE NOTIFY US IMMEDIATELY BY TELEPHONE AND RETURN THE ORIGINAL MESSAGE TO US BY MAIL. THANK YOU.

PATENT
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Total number of pages comprising cover sheet: 1